

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of claims:

1. (Currently Amended) A siloxane-based resin prepared by hydrolyzing and condensing a silane-based monomer having the structure of Formula 1, and at least one monomer selected from the group consisting of compounds of Formulas 2 to 4, in an organic solvent in the presence of an acid or alkaline catalyst and water:

Formula 1

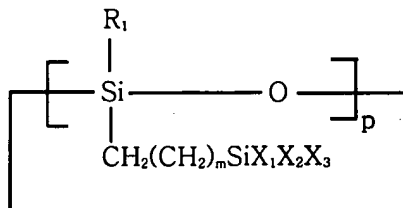


wherein,

k is an integer of 1-10; and

Y₁, Y₂ and Y₃ are independently a C₁-C₃ alkyl group, a C₁-C₁₀ alkoxy group, or a halogen atom, provided that at least one of them is hydrolyzable,

Formula 2



wherein,

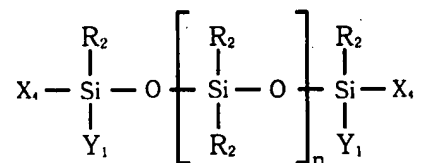
R₁ is a C₁-C₃ alkyl group, or a C₆-C₁₅ aryl group;

X₁, X₂ and X₃ are independently a hydrogen atom, a C₁-C₃ alkyl group, a C₁-C₁₀ alkoxy group, or a halogen atom, provided that at least one of them is hydrolyzable;

m is an integer of 0-10; and

p is an integer of 3-8,

Formula 3



wherein,

R₂ is a C₁-C₃ alkyl group, or a C₆-C₁₅ aryl group;

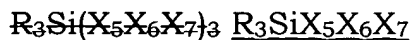
X₄ is a hydrogen atom, or a C₁-C₁₀ alkoxy group;

Y₁ is a hydrogen atom, a C₁-C₃ alkyl group or a C₁-C₁₀ alkoxy group;

and

n is an integer of 0-10, and

Formula 4



wherein,

R₃ is a C₁-C₃ alkyl group, or a C₆-C₁₅ aryl group;

X₅, X₆ and X₇ are independently a hydrogen atom, a C₁-C₃ alkyl group,

a C₁-C₁₀ alkoxy group, or a halogen atom, provided that at least one of them is hydrolyzable.

2. (Original) The siloxane-based resin according to claim 1, wherein the molar ratio of the monomer of Formula 1 to the monomer selected from the group consisting of compounds of Formulas 2 to 4 is 1:99 to 99:1.

3. (Original) The siloxane-based resin according to claim 1, wherein the catalyst is selected from the group consisting of hydrochloric acid, nitric acid, benzene sulfonic acid, oxalic acid, formic acid, potassium hydroxide, sodium hydroxide, triethylamine, sodium bicarbonate, pyridine, and mixtures thereof.

4. (Original) The siloxane-based resin according to claim 1, wherein the molar ratio of the monomer to the catalyst is 1:0.000001 to 1:10.

5. (Original) The siloxane-based resin according to claim 1, wherein the molar ratio of the monomer to water is 1:1 to 1:1000.

6. (Original) The siloxane-based resin according to claim 1, wherein the hydrolysis and condensation reactions are performed at 0-200°C for 0.1-100 hours.

7. (Original) The siloxane-based resin according to claim 1, wherein the organic solvent is selected from the group consisting of an aliphatic hydrocarbon solvent, an aromatic hydrocarbon solvent, a ketone-based solvent, an ether-based solvent, an acetate-based solvent, an alcohol-based solvent, an amide-based solvent, a silicon-based solvent, and mixtures thereof.

8. (Original) The siloxane-based resin according to claim 1, wherein the weight average molecular weight of the resin is 3,000 to 300,000.

9. (Original) A method of preparing a semiconductor interlayer insulating film which comprises:

providing a liquid coating composition by dissolving the siloxane-based resin according to claim 1 in an organic solvent;

coating a silicon wafer with the liquid coating composition to form a coating film; and

heat-curing the coating film.

10. (Original) The method according to claim 9, wherein the siloxane-based resin is mixed with a porogen so that the weight ratio of the resin to the porogen is 99:1-30:70.

11. (Original) The method according to claim 10, wherein the porogen is selected from the group consisting of cyclodextrin, polycaprolactone and derivatives thereof.

12. (Original) The method according to claim 9, wherein the organic solvent is selected from the group consisting of an aliphatic hydrocarbon solvent, an aromatic hydrocarbon solvent, a ketone-based solvent, an ether-based solvent, an acetate-based solvent, an alcohol-based solvent, an amide-based solvent, a silicon-based solvent, and mixture thereof.

13. (Original) The method according to claim 9, wherein the weight ratio of solid component containing the siloxane-based resin and the porogen is 5-70 wt% based on the total weight of the composition.

14. (Original) The method according to claim 9, wherein the liquid coating composition is applied to the silicon wafer through spin coating.

15. (Original) The method according to claim 9, wherein the heat curing is performed at a temperature of 150-600°C for 1-150 min.

16. (Original) A semiconductor interlayer insulating film, comprising the siloxane-based resin of claim 1.

17. (Original) The semiconductor interlayer insulating film according to claim 16, wherein micropores are formed throughout the film by the use of a porogen.

18. (Original) The semiconductor interlayer insulating film according to claim 17, wherein the porogen is selected from the group consisting of cyclodextrin, polycaprolactone and derivatives thereof.

CLAIMS 19-20 (CANCELLED)